Silicon Carbide Schottky Diode

1200 V, 10 A

FFSP10120A

Description

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size and cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 100 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery/No Forward Recovery
- This Device is Pb−Free, Halogen Free/BFR Free and RoHS Compliant

Applications

- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuits

ON Semiconductor®

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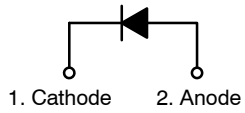
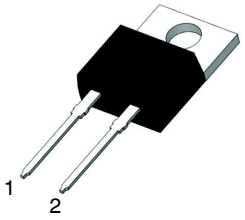
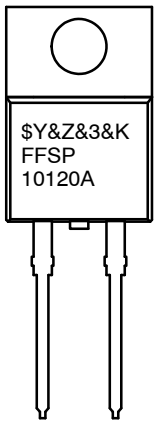


Schottky Diode



TO−220−2LD
CASE 340BB

MARKING DIAGRAM



$Y	= ON Semiconductor Logo
&Z	= Assembly Plant Code
&3	= Numeric Date Code
&K	= Lot Code
FFSP10120A	= Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Symbol	Parameter		Value	Unit
V_{RRM}	Peak Repetitive Reverse Voltage		1200	V
E_{AS}	Single Pulse Avalanche Energy (Note 1)		100	mJ
I_F	Continuous Rectified Forward Current @ T_C < 148°C		10	A
$I_{F,Max}$	Non-Repetitive Peak Forward Surge Current	T_C = 25°C, 10 μs	850	A
		T_C = 150°C, 10 μs	800	A
$I_{F,SM}$	Non-Repetitive Forward Surge Current	Half−Sine Pulse, t_p = 8.3 ms	90	A
$I_{F,RM}$	Repetitive Forward Surge Current	Half−Sine Pulse, t_p = 8.3 ms	35	A
P_{TOT}	Power Dissipation	T_C = 25°C	168	W
		T_C = 150°C	28	W
T_J, T_{STG}	Operating and Storage Temperature Range		−55 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. E_{AS} of 100 mJ is based on starting T_J = 25°C, L = 0.5 mH, I_{AS} = 20 A, V = 150 V.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max	0.89	°C/W

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
V_F	Forward Voltage	I_F = 10 A, T_C = 25°C	–	1.45	1.75	V
		I_F = 10 A, T_C = 125°C	–	1.7	2.0	
		I_F = 10 A, T_C = 175°C	–	2.0	2.4	
I_R	Reverse Current	V_R = 1200 V, T_C = 25°C	–	–	200	μA
		V_R = 1200 V, T_C = 125°C	–	–	300	
		V_R = 1200 V, T_C = 175°C	–	–	400	
Q_C	Total Capacitive Charge	V = 800 V	–	62	–	nC
C	Total Capacitance	V_R = 1 V, f = 100 kHz	–	612	–	pF
		V_R = 400 V, f = 100 kHz	–	58	–	
		V_R = 800 V, f = 100 kHz	–	47	–	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Quantity
FFSP10120A	FFSP10120A	TO−220−2LD	Tube	50 Units

TYPICAL CHARACTERISTICS

(T_J = 25°C unless otherwise noted)

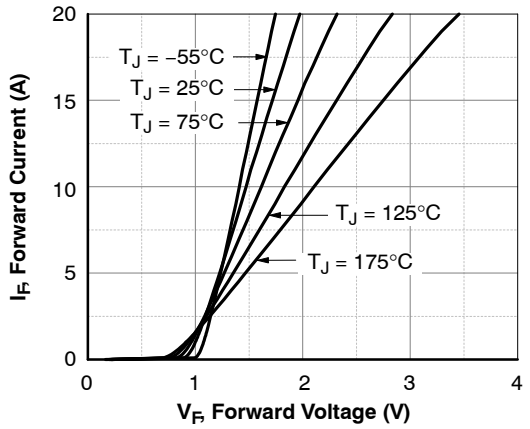


Figure 1. Forward Characteristics

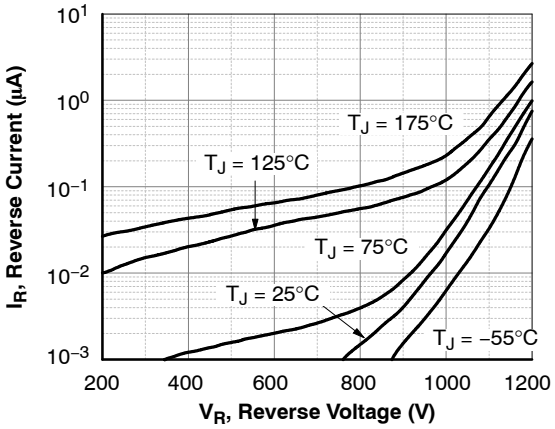


Figure 2. Reverse Characteristics

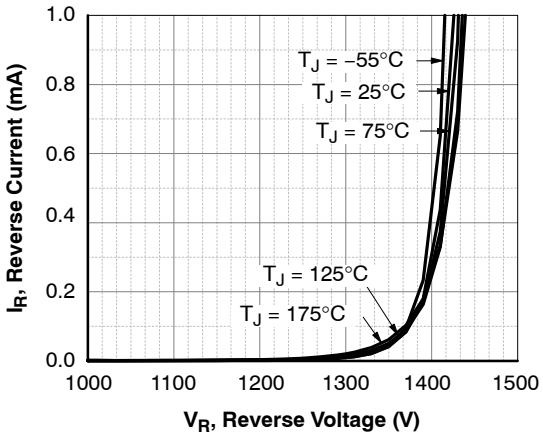


Figure 3. Reverse Characteristics

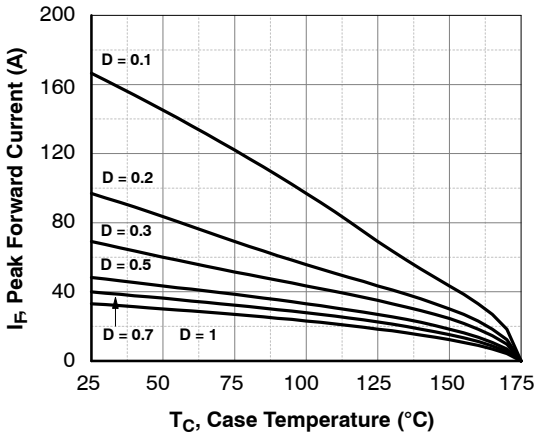


Figure 4. Current Derating

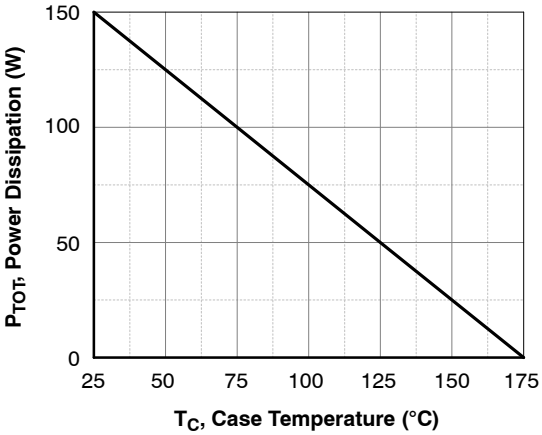


Figure 5. Power Derating

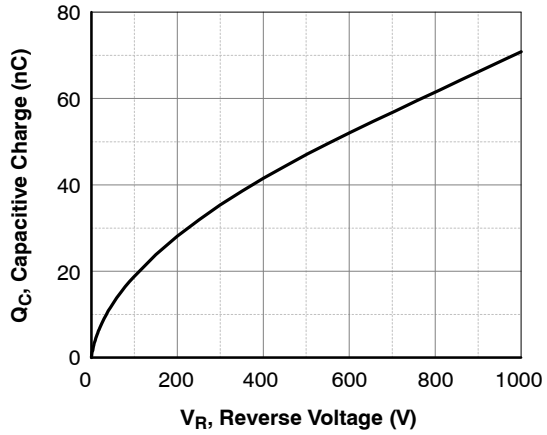


Figure 6. Capacitive Charge vs. Reverse Voltage

TYPICAL CHARACTERISTICS (Continued)

(T_J = 25°C unless otherwise noted)

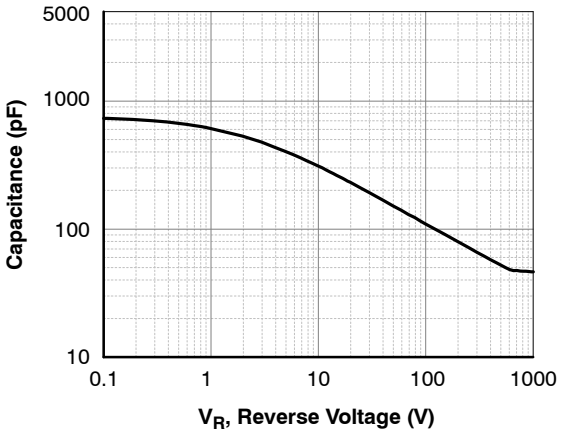


Figure 7. Capacitance vs. Reverse Voltage

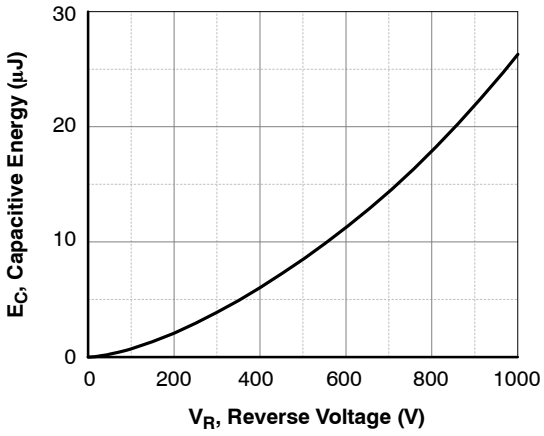


Figure 8. Capacitance Stored Energy

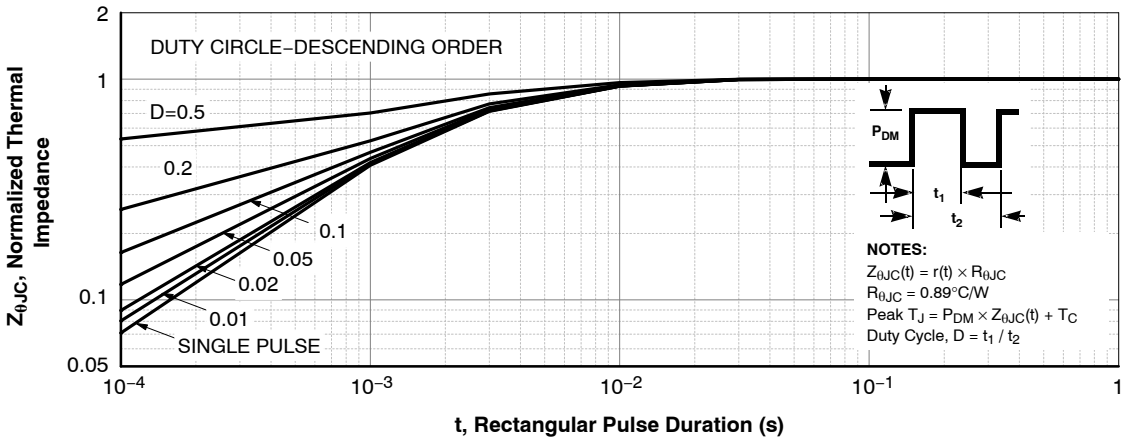
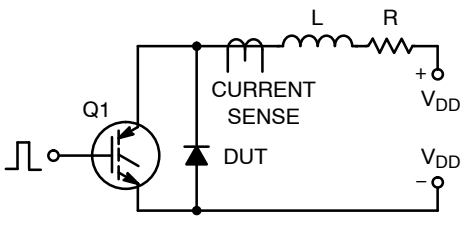


Figure 9. Junction−to−Case Transient Thermal Response Curve

TEST CIRCUIT AND WAVEFORMS

L = 0.5 mH
R < 0.1 Ω
V_{DD} = 50 V
EAVL = 1/2LI2 [$V_{R(AVL)}$ / ($V_{R(AVL)}$ − V_{DD})]
Q1 = IGBT (BV_{CES} > DUT $V_{R(AVL)}$)



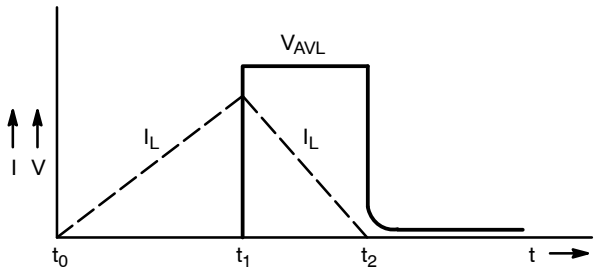


Figure 10. Unclamped Inductive Switching Test Circuit & Waveform

TO−220−2LD
CASE 340BB
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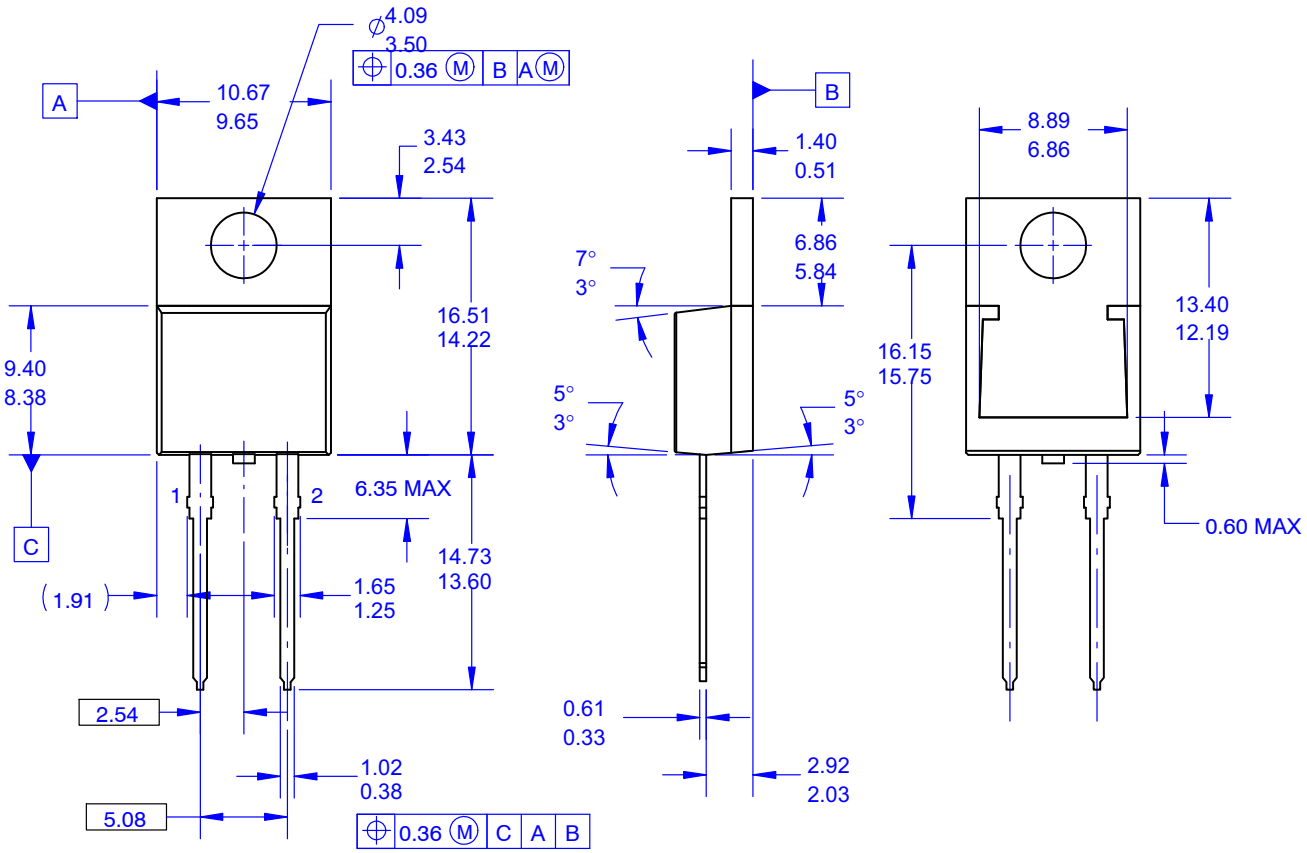

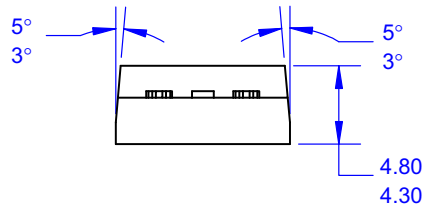

NOTES:
A. PACKAGE REFERENCE: JEDEC TO220,ISSUE K, VARIATION AC,DATED APRIL 2002.
B. ALL DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSION AND TOLERANCE AS PER ASME Y14.5−2009.
D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

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DESCRIPTION:	**TO−220−2LD**		**PAGE 1 OF 1**

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Email Requests to: orderlit@onsemi.com

ON Semiconductor Website: www.onsemi.com

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North American Technical Support:
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